

## CURRENT LEAD FREE SERIAL EEPROMS OFFERED BY ISSI

Lead Free

### Top Mark

IS24C01-2GL  
IS24C01-2GLI  
IS24C01-3GL  
IS24C01-3GLI  
IS24C01-2ZL  
IS24C01-2ZLI  
IS24C01-3ZL  
IS24C01-3ZLI  
IS24C01-3ZLI  
IS24C01-2SL  
IS24C01-2SLI  
IS24C01-3SL  
IS24C01-3SLI  
IS24C01-2PL  
IS24C01-2PLI  
IS24C01-3PL  
IS24C01-3PLI

IS24C02-2GL  
IS24C02-2GLI  
IS24C02-3GL  
IS24C02-3GLI  
IS24C02-2ZL  
IS24C02-2ZLI  
IS24C02-3ZL  
IS24C02-3ZLI  
IS24C02-2SL  
IS24C02-2SLI  
IS24C02-3SL  
IS24C02-3SLI  
IS24C02-2PL  
IS24C02-2PLI  
IS24C02-3PL  
IS24C02-3PLI



### Q: How do we differentiate Lead Free Product from Non-Lead Free Product?

**A:** The package code for Lead Free is different from a Non Lead Free Product. For example, a Non-Lead Free 8-pin SOIC has a package designator of 'G' and the Lead Free 8-pin SOIC has a package designator of 'GL'. We simply added a 'L' to the old package code.

### Q: Is it RoHS Compliant?

RoHS - European Union's Restriction on Hazardous Substances Directive (which bans the industry's use of lead, mercury, cadmium, hexavalent chromium and two brominated flame retardants –PBB and PBDE).

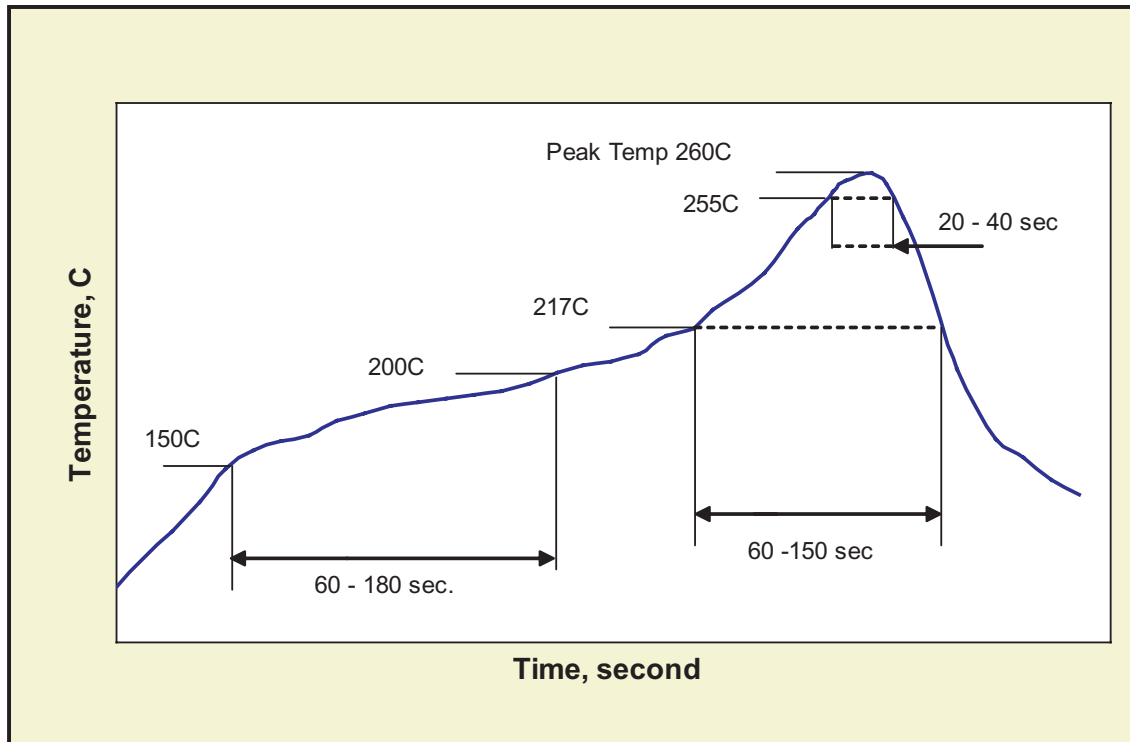
**A:** Yes

### Q: What is the plating for lead frame finger?

**A:** 100% Matte Tin

\* More options available upon request

## IR Reflow Temperature Profile (Pb-Free)



### ISSI Spec

Average ramp-up rate	< 3°C/sec
Preheat temperature 150°C to 200°C	60 – 180 sec
Temperature maintained above 217°C	60 – 150 sec
Peak temperature	260°C
Temperature > 255°C	20 – 40 sec
Ramp-down rate	< 6°C/sec